	Application No.	Applicant(s)
Notice of Allowability	10/633,208	WENG ET AL.
	Examiner	Art Unit
	David Nhu	2818
The MAILING DATE of this communication appears on the cover sheet with the correspondence address All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS. This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.		
1. This communication is responsive to <u>11/2/04</u> .		
2. The allowed claim(s) is/are 1-47.		
3. The drawings filed on 31 July 2003 are accepted by the Examiner.		
 4. Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some* c) None of the: Certified copies of the priority documents have been received. Certified copies of the priority documents have been received in Application No. Copies of the certified copies of the priority documents have been received in this national stage application from the International Bureau (PCT Rule 17.2(a)). * Certified copies not received: Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application. THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. 5. A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF 		
INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient.		
6. CORRECTED DRAWINGS (as "replacement sheets") must be submitted.		
(a) 🗔 including changes required by the Notice of Draftsperson's Patent Drawing Review (PTO-948) attached		
1) hereto or 2) to Paper No./Mail Date		
(b) ☐ including changes required by the attached Examiner's Amendment / Comment or in the Office action of Paper No./Mail Date		
Identifying indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet. Replacement sheet(s) should be labeled as such in the header according to 37 CFR 1.121(d).		
7. DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL.		
*		
Attachment(s) 1. ☑ Notice of References Cited (PTO-892)	5. Notice of Informal F	Patent Application (PTO-152)
2. \square Notice of Draftperson's Patent Drawing Review (PTO-948)	6. Interview Summary	
3. Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date	· · · · · · · · · · · · · · · · · ·	Paper No./Mail Date 7.
Examiner's Comment Regarding Requirement for Deposit 8. Exam	9. 🔲 Other	ent of Reasons for Allowance

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REASONS FOR ALLOWANCE

1. Claims 1-47 are allowed.

- 2. The following is an examiner's statement of reasons for allowance: None of the references of record teaches or suggests as cited in claims 1, 30, 44: using said solutions, forming solution-processed thin films including conductive solution-processed thin film contacts, semiconductor solution-processed thin film active regions, and dielectric solution-processed thin film isolations in a sequence and organization to form a solution-processed thin film structure capable of transistor operation; subsequent to a deposit of semiconductor material contained in a solvent used for forming of the semiconductor solution-processed thin film active regions but prior to deposit of any subsequent layers, selectively laser heating the semiconductor material contained in a solvent used for forming of the semiconductor solutionprocessed thin film active regions to vaporize the solvent to form the semiconductor solution processed thin film active regions (as cited in claims 1); forming solution-processed thin film layers into a transistor structure; during said forming, selectively heating semiconductor portions of the transistor structure via a laser, to modify the material state of semiconductor material from a solution deposited material state to a thin film layer material state (as cited in claim 30); refining the rough pattern by selective laser ablation of the drain and source contacts; completing a semiconductor active region by selective laser heating the solution of the semiconductor material to vaporize solvent from the solution and leave a thin film of the semiconductor material (as cited in claim 44).
- 3. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the

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issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

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Conclusion

4. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure: Mukai (5,264,072): Method for Recrystallizing Conductive Films by an Indirect-

Heating with a Thermal Conduction Controlling Layer.

5. Any inquiry concerning this communication on earlier communications from the examiner

should be directed to David Nhu, (571)272-1792. The examiner can normally be reached

on Monday-Friday from 7:30 AM to 5:00 PM.

The examiner's supervisor, David Nelms can be reached on (571)272-1787.

The fax phone number for the organization where this application or proceeding is assigned is

(703)872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should

be directed to the receptionist whose telephone number is (703) 308-0956

David Nhu

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November 9, 2004

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